## ABSTRACT OF THE DISCLOSURE

A semiconductor device of chip-on-chip structure is provided which includes a first semiconductor chip and a second semiconductor chip bonded onto the first semiconductor chip in stacked relation. In one embodiment, a noise shield film is provided between the first semiconductor chip and the second semiconductor chip for shielding against a radiation noise from the second semiconductor chip. In another embodiment, a metal film is provided between the first semiconductor chip and the second semiconductor chip to provide a heat release path for releasing heat generated by the second semiconductor chip.